ABSOCIATION CONNECTING ELECTRONICS INDUSTRIES® MAterial Comp © Copyright 2005. 1 international and Par	PC, Bannock	burn, Illinois. A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declar the declaration	ration of n encom	the substance passes all low	s within the er level mat	manufactur erials for wl	er listed ite hich the m	em. Note anufactur	: if the item is an as rer has engineering	ssembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information				
Supplier Information															
Company name*	Company uni	Company unique ID			Unique ID Authority					Response Date*					
onsemi											2024-05-06				
Contact Name Title - Contact			ct	PI			Phone - Contact*					Email - Contact*			
Product-Env-Stewards Product H			roduct Enviro Compliance			NA					Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Represen			sentative P			Phone - Representative*				Email - Representative*					
Product-Env-Stewards	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com							
Requester Item Number	Requester Item Number Mfr Iter		n Number Mfr Item Name			Effective Date Version Manufacturing Sit		ing Site	V	Veight*	UOM	Unit Type			
	FAN401	FAN4010IL6X-F113 Curre		Current Sense Amplifier		2024-05-06		TH2		2	2.035 mg		Each		
Ianufacturing Proccess Informa	tion												I	1	
Terminal Plating / Grid Array Ma	aterial	Ferminal Base A	Alloy	J-STD-020 MSL Rating		Peak Process Body Temper		ody Temperat	ture Max Time at Peak Ter		Temperatu	berature Number of Reflow Cycles		cles	
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy 1		1		260		C	30		second	ls 3			
omments															
vel 1 - maximum time at peak temperatu	ire during so	ldering is 10-3	0 seconds												
or more information regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material Weight		Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.055	mg	Supplier	Silicon (Si)	7440-21-3		0.055	mg
Die Attach	0.014	mg	Supplier	Phenolic Resin-2	54208-63-8		0.007	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.007	mg
Lead Frame	0.562	mg	Supplier	Zinc (Zn)	7440-66-6		0.001	mg
			Supplier	Iron (Fe)	7439-89-6		0.014	mg
			Supplier	Copper (Cu)	7440-50-8		0.547	mg
			Supplier	Phosphorus (P)	7723-14-0		-0	mg
Mold Compound-Black	1.34	mg	Supplier	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'- tetramethylbiphenyl	85954-11-6		0.268	mg
			Supplier	Carbon Black (C)	1333-86-4		0.013	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		0.992	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.067	mg
Plating	0.026	mg	Supplier	Palladium (Pd)	7440-05-3		0.002	mg
			В	Nickel (Ni)	7440-02-0		0.024	mg
			Supplier	Gold (Au)	7440-57-5		-0	mg
Wire Bond - Au	0.038	mg	Supplier	Gold (Au)	7440-57-5		0.038	mg